

Abstract

A stacked modular jack connector having low cross talk and low combined stack height is disclosed. Low stack height is achieved by disposing contact terminals for stacked pairs of receptacles in a single
5 coplanar array of interleaved terminals. The arrays are located between the receptacles. One receptacle of each pair is laterally offset from the other. For Ethernet applications, cross talk is minimized by arranging first, second, third and sixth terminals of a ten terminal array into a contact group of the first receptacle and fifth, eighth, ninth and tenth
10 terminals of the array into a contact group of the second receptacle. Circuit board space requirements are minimized by arranging the terminal tails of both groups of terminals in a single line.

